

87	77	(compar\$3 with (reference) with (pattern or die or circuit or image) with (difference or subtract\$4) with (select\$4 or choos\$4 or determin\$4)) and inspect\$4	USPAT; US-PGPUB	2002/04/12 17:06
90	5	die adj die adj inspection	USPAT; US-PGPUB	2002/04/12 17:06
93	107	die adj2 die with inspection	USPAT; US-PGPUB	2002/04/12 17:07
96	1	(die adj2 die with inspection) and (reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 17:08
99	16	(die adj2 die with inspection) and (reference or template or model) near (choos\$4 or determin\$4 or select\$4)	USPAT; US-PGPUB	2002/04/12 17:09

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L Number	Hits	Search Text	DB	Time stamp
1	609	(reference or template or model) near die	USPAT; US-PGPUB	2002/04/12 16:27
4	4	((reference or template or model) near die) same image near (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:24
7	19	((reference or template or model) near die) with select\$4	USPAT; US-PGPUB	2002/04/12 16:00
10	11	((reference or template or model) near die) near2 (choos\$4 or determin\$4)	USPAT; US-PGPUB	2002/04/12 16:25
13	27	((reference or template or model) near die) with (defect\$4 or flaw)	USPAT; US-PGPUB	2002/04/12 16:04
16	14539	(reference or template or model) with (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:12
19	1403	(reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:13
25	4	((reference or template or model) near die) with subtract\$4	USPAT; US-PGPUB	2002/04/12 16:14
22	99	(reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 17:07
28	18	((reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image) and inspect\$4	USPAT; US-PGPUB	2002/04/12 16:19
31	1	("4908871").PN.	USPAT; US-PGPUB	2002/04/12 16:21
34	2	select\$4 adj reference adj die	USPAT; US-PGPUB	2002/04/12 16:22
37	3	select\$4 adj reference adj die	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:23
42	1	2000-656045.NRAN.	DERWENT	2002/04/12 16:23
43	290	(reference or template or model) near die	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:24
48	1	((reference or template or model) near die) same image near (difference or subtract\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:24
53	8	((reference or template or model) near die) near2 (choos\$4 or determin\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:26
58	2	((reference or template or model) near die) and image with (difference or subtract\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:27
63	1902	(382/141-154).CCLS.	USPAT; US-PGPUB	2002/04/12 16:27
66	20	(reference or template or model) near die and ((382/141-154).CCLS.)	USPAT; US-PGPUB	2002/04/12 16:31
69	166	reference adj die	USPAT; US-PGPUB	2002/04/12 16:40
72	6891	reference adj circuit	USPAT; US-PGPUB	2002/04/12 16:40
75	49	382/\$.ccls. and (reference adj circuit)	USPAT; US-PGPUB	2002/04/12 16:41
78	455	select\$4 with reference adj pattern	USPAT; US-PGPUB	2002/04/12 16:42
81	4	(select\$4 with reference adj pattern) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 16:43
84	667	compar\$3 with (reference) with (pattern or die or circuit or image) with (difference or subtract\$4) with (select\$4 or choos\$4 or determin\$4)	USPAT; US-PGPUB	2002/04/12 16:46

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*DeJong, C.D.*Simulation Conference, 2001. Proceedings of the Winter , Volume: 2 , 2001
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*Guo, Y.; Jie-Hua Zhao*Thermal and Thermomechanical Phenomena in Electronic Systems, 2000. ITH
2000. The Seventh Intersociety Conference on , 2000 -399[\[Abstract\]](#) [\[PDF Full-Text \(524 KB\)\]](#) **CNF****3 A TDDDB model of Si/sub 3/N/sub 4/-based capacitors in GaAs MMIC**
*Scarpulla, J.; Eng, D.C.; Olson, S.R.; Wu, C.-S.*Reliability Physics Symposium Proceedings, 1999. 37th Annual. 1999 IEEE Int
, 1999

Page(s): 128 -137

[\[Abstract\]](#) [\[PDF Full-Text \(804 KB\)\]](#) **CNF****4 A combined method for the global optimization using radial basis fu**
and deterministic approach*Ishikawa, T.; Tsukui, Y.; Matsunami, M.*

Magnetics, IEEE Transactions on , Volume: 35 Issue: 3 Part: 1 , May 1999

Page(s): 1730 -1733

[\[Abstract\]](#) [\[PDF Full-Text \(304 KB\)\]](#) [JNL](#)

5 Thermal fatigue reliability analysis of redistributed flip chip assemb

Vandevelde, B.; Beyne, E.

Electronic Components & Technology Conference, 1998. 48th IEEE , 1998

Page(s): 37 -44

[\[Abstract\]](#) [\[PDF Full-Text \(1204 KB\)\]](#) [CNF](#)

6 Statistical model for spatial correlation in thin film deposition and re growth

Carlen, E.T.; Mastrangelo, C.H.

Semiconductor Manufacturing, IEEE Transactions on , Volume: 11 Issue: 3 , A

Page(s): 511 -521

[\[Abstract\]](#) [\[PDF Full-Text \(404 KB\)\]](#) [JNL](#)

7 Shape optimization of polymer extrusion die by three-dimensional f simulation

Su Yeon Na; Tai-Yong Lee

High Performance Computing on the Information Superhighway, 1997. HPC A 1997

Page(s): 601 -604

[\[Abstract\]](#) [\[PDF Full-Text \(280 KB\)\]](#) [CNF](#)

8 The appropriateness of plastic encapsulated microcircuits in a speci wooden-round application

Gardner, J.R.

Reliability, IEEE Transactions on , Volume: 45 Issue: 1 , March 1996

Page(s): 10 -18

[\[Abstract\]](#) [\[PDF Full-Text \(916 KB\)\]](#) [JNL](#)

9 Known Good Die Selection Tradeoffs: A Cost Model

Murphy, C.F.

Multichip Modules, 1994. Proceedings of the 1994 International Conference on 13-15, 1994

Page(s): 261 -265

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) [CNF](#)

10 A thermal evaluation of multichip module (MCM) materials and des

Kuhlman, M.A.; Sehitoglu, H.

Semiconductor Thermal Measurement and Management Symposium, 1992.

SEMI-THERM VIII., Eighth Annual IEEE , 1992
Page(s): 110 -118

[\[Abstract\]](#) [\[PDF Full-Text \(560 KB\)\]](#) [CNF](#)

11 Effects of die pad anchoring on package interfacial integrity

Nguyen, L.T.; Michael, M.M.

Electronic Components and Technology Conference, 1992. Proceedings., 42nd
Page(s): 930 -938

[\[Abstract\]](#) [\[PDF Full-Text \(868 KB\)\]](#) [CNF](#)

12 Silver-induced volatile species generation from conductive die attachment adhesives

Phillips, T.E.; deHaas, N.; Goodwin, P.G.; Benson, R.C.

Electronic Components and Technology Conference, 1992. Proceedings., 42nd
Page(s): 225 -233

[\[Abstract\]](#) [\[PDF Full-Text \(656 KB\)\]](#) [CNF](#)

13 Silver-induced volatile species generation from conductive die attachment adhesives

Phillips, T.E.; deHaas, N.; Goodwin, P.G.; Benson, R.C.

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part Volume: 15 Issue: 6 , Dec. 1992
Page(s): 956 -963

[\[Abstract\]](#) [\[PDF Full-Text \(780 KB\)\]](#) [JNL](#)

14 Thermal modeling and experimental techniques for microwave bipolar devices

Negus, K.J.; Franklin, R.W.; Yovanovich, M.M.

Semiconductor Thermal and Temperature Measurement Symposium, 1989.
SEMI-THERM V., Fifth Annual IEEE , 1989
Page(s): 63 -72

[\[Abstract\]](#) [\[PDF Full-Text \(964 KB\)\]](#) [CNF](#)

15 Thermal modeling and experimental techniques for microwave bipolar devices

Negus, K.J.; Franklin, R.W.; Yovanovich, M.M.

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part Volume: 12 Issue: 4 , Dec. 1989

Page(s): 680 -689

[\[Abstract\]](#) [\[PDF Full-Text \(1064 KB\)\]](#) [JNL](#)

16 Material effects on the performance and reliability of high-power m dual-in-line packages

DiOrio, M.; Pinamaneni, S.

Electronics Components Conference, 1988., Proceedings of the 38th , 1988

Page(s): 406 -410

[\[Abstract\]](#) [\[PDF Full-Text \(300 KB\)\]](#) [CNF](#)

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